

品名:<u>VGAP-CLB-AS-A1</u> <u>History List</u>

版本		III · VOAI ·CLD·AO·AI					I IISTOI Y LIST
P1 & P8						VALID	
A1   林豪建	A0	黃啟傑	All	正式發行	2013/10/01	2013/10/15	N/A
A2       林豪建       P3       Layout 修正尺寸圖示       2015/09/07       2015/09/11       ECN20153701         A3       林豪建       P8       修改 Operating temperature range 變更前: -40 ~ +105°C       2017/03/31       2017/04/07       ECN20171415         A4       林豪建       P1 & P8       新增 AEC-Q200 敘述       2017/04/20       2017/05/02       ECN20171737         A5       彭小尹       P8       再新可靠度測試修件       2018/08/23       依 PLM	A1	林豪建	P2	W1、L1 、W2、L2 尺寸、圖面 修正標示、新增 Pin 放置圖示	2015/07/09	2015/07/20	ECN20152819
A3       林豪建       P8       temperature range 變更前: -40 ~ +105°C 變更後: -40 ~ +125°C       2017/03/31       2017/04/07       ECN20171415         A4       林豪建       P1 & P8       新增 AEC-Q200 敘述       2017/04/20       2017/05/02       ECN20171737         A5       彭小尹       P8       再新可靠度測試修件:       2018/08/23       依 PLM	A2	林豪建	P3		2015/09/07	2015/09/11	ECN20153701
A5	A3	林豪建	P8	temperature range 變更前:-40~+105°C	2017/03/31	2017/04/07	ECN20171415
1 //6   62/1/22   1   1   1   1   1   1   2   1   1	A4	林豪建	P1 & P8	新增 AEC-Q200 敘述	2017/04/20	2017/05/02	ECN20171737
	A5	彭少君	P8	更新可靠度測試條件	2018/08/22		

# **VGAP-CLB-AS-A1 Specification**

# 1. Features and Application:

- (1) This product is manufactured in ISO/TS16949 certified production factory.
- (2) This product is qualified according to AEC-Q200.
- (3) This product is for 2.4/5 GHz Dual Band WiFi, 802.11 b/g/n, Zigbee, Bluetooth,...

# 2. Explanation of Part Number:

VGAP - 
$$\frac{C}{(1)}$$
  $\frac{LB}{(2)}$  -  $\frac{A}{(3)}$   $\frac{S}{(4)}$  -  $\frac{A1}{(5)}$ 

(1) Product Type: Chip Antenna

(2) Center Frequency/Band Code: 2.4/5 GHz Dual-Band

(3) Size Code: 5.0\*3.6 mm (Length \* Width)

(4) Special Code : RoHS Compliant(5) Design Revision Code : Rev.1

# 3. Electrical Specification:

Item	Specification Sp		
Frequency Band	2400 ~ 2500 MHz	5000 ~ 6000 MHz	
Polarization	Linear		
Impedance	50 ohm Typ.		
VSWR	Less than 2.0	Less than 2.0	
*Peak Gain	3.2 dBi Typ.	3.5 dBi Typ.	
*Peak Efficiency	74.8% Typ.	81.6% Typ.	

\* Test condition: Test board size 80\*40 mm

Matching circuit may be required

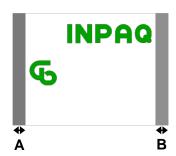
UNLESS OTHER SPECIFIED TOLERANCES ON:				
$X=\pm$ $X.X=\pm$	X.XX =	G	INPAQ TECHNOLOGY CO	)., LTD.
ANGLES=±	HOLEDIA=±			·
SCALE:	UNIT : mm		IGS AND SPECIFICATIONS ARE THE PR	
DRAWN BY:彭少君	CHECKED BY:黄月碧		OLOGY CO.,LTD.AND SHALL NOT BE REPR IE BASIS FOR THE MANUFACTURE OF	
DESIGNED BY:彭少君	APPROVED BY:謝立庭	APPARATUS C	OR DEVICES WITHOUT PERMISSION	
TITLE: VGAP-CLB-AS-A1 Specification		DOCUMENT	ENS000061960	SPEC REV.
III EE : VOAI -OEB-AO-AT	Opecinication	NO.	LN300001900	A5

# 4. Physical Dimension:

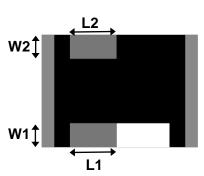


**Marking is Green** 

# Top view



### **Bottom view**

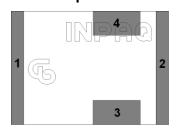


L	$5.20 \pm 0.30$
w	$3.70 \pm 0.30$
н	$0.70 \pm 0.15$
Α	$0.45 \pm 0.25$
В	$0.45 \pm 0.25$
L1	$1.60 \pm 0.20$
W1	$0.62 \pm 0.20$
L2	$1.50 \pm 0.20$
W2	$0.62 \pm 0.20$

(Unit: mm)

Pin Configuration

**Top View** 



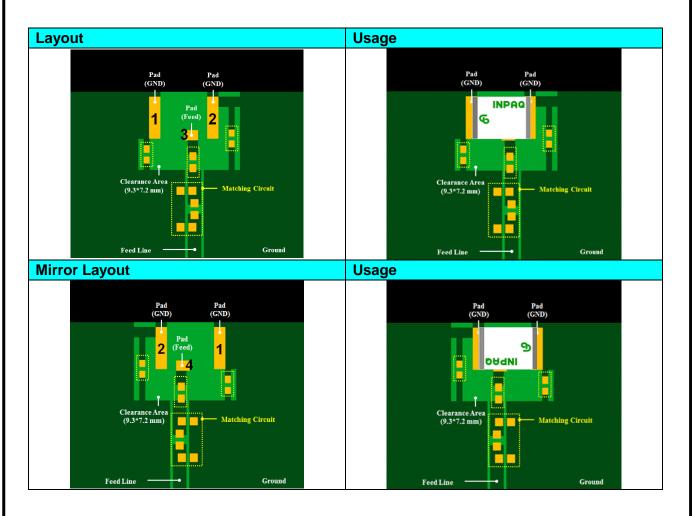
### **Pin Assignments**

Layout		
Pin Function		
1	GND	
2	2 GND	
3 Feed		
4 No connect		

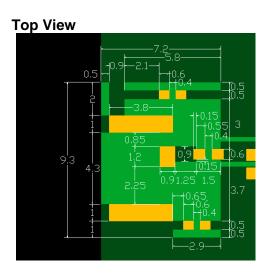
Mirror Layout			
Pin	Function		
1	GND		
2	GND		
3	No connect		
4	Feed		

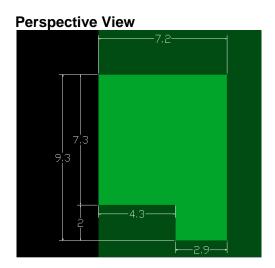
UNLESS OTHER SPECIFIE	D TOLERANCES ON :			
$X=\pm$ $X.X=\pm$	X.XX =	(Ta	INPAQ TECHNOLOGY CO	)., LTD.
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IIIILL : VOAI -CLB-AG-A	(1 Specification	NO.	LN300001900	A5

# 5. Recommend PCB Layout:



### **Pad Dimensions on PCB Layout**



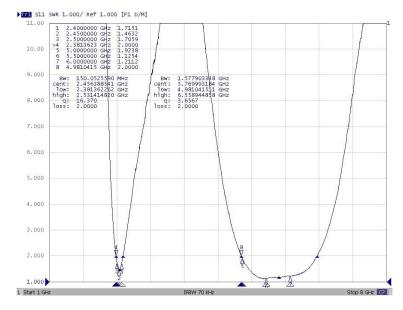


(Unit: mm)

UNLESS OTHER SPECIFIED  X=± X.X=±  ANGLES=±	TOLERANCES ON : X.XX= HOLEDIA=±	G	INPAQ TECHNOLOGY CO	)., LTD.
SCALE:	UNIT : mm		IGS AND SPECIFICATIONS ARE THE PROPOSED OF THE	
DRAWN BY:彭少君 DESIGNED BY:彭少君	CHECKED BY: 黃月碧 APPROVED BY: 謝立庭	USED AS TI	HE BASIS FOR THE MANUFACTURE OF OR DEVICES WITHOUT PERMISSION	
TITLE: VGAP-CLB-AS-A1 Specification		DOCUMENT NO.	ENS000061960	SPEC REV.

# 6. Electrical Characteristics:

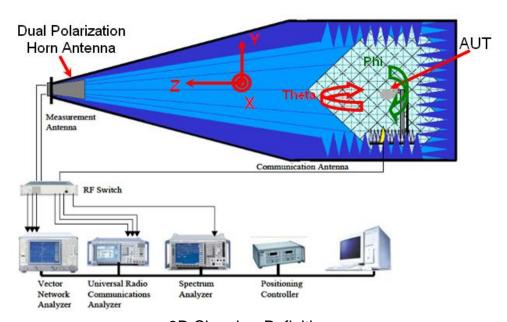
#### **VSWR**



Frequency (MHz)	VSWR
2400	1.7
2450	1.5
2500	1.7
5000	1.9
5500	1.1
6000	1.2

#### **Radiation Pattern**

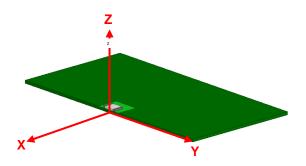
The Gain pattern is measured in INPAQ's FAR-field chamber. DUT is placed on the table of rotator, a standard horn antenna and Vector Network Analyzer is used to collect data.

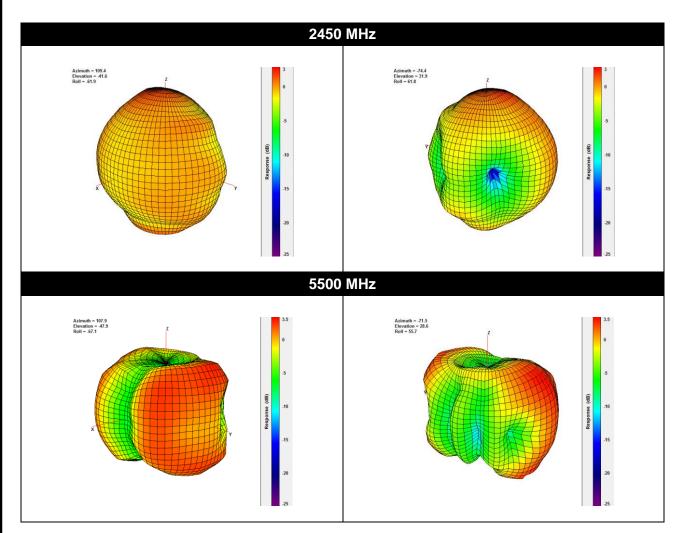


3D Chamber Definition

UNLESS OTHER SPECIFIED	TOLERANCES ON:			
$X=\pm$ $X.X=\pm$	X.XX =	G <sub>2</sub>	INPAQ TECHNOLOGY CO	)., LTD.
ANGLES=±	HOLEDIA=±			·
SCALE:	UNIT: mm	THIS DRAWIN	IGS AND SPECIFICATIONS ARE THE PR	OPERTY OF
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DESIGNED BY:彭少君	APPROVED BY:謝立庭	APPARATUS C	OR DEVICES WITHOUT PERMISSION	
TITLE: VGAP-CLB-AS-A1 Specification		DOCUMENT	ENS000061960	SPEC REV.
TITLE : VOAI -GEB-AG-A	Ореспісаціон	NO.	LN300001900	A5

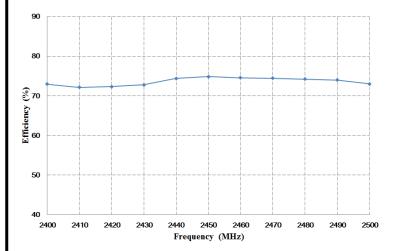
# 3D Gain Pattern



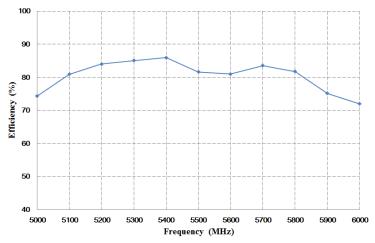


UNLESS OTHER SPECIFIED X=± X.X=±	TOLERANCES ON: X.XX=	G	INPAQ TECHNOLOGY CO	LTD
	HOLEDIA=±	40	INFAQ ILCIINOLOGI CC	)., LID.
SCALE:	UNIT: mm	THIS DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY O		
DRAWN BY:彭少君	CHECKED BY:黄月碧		OLOGY CO.,LTD.AND SHALL NOT BE REPRI IE BASIS FOR THE MANUFACTURE OF	
DESIGNED BY:彭少君	APPROVED BY:謝立庭	APPARATUS C	OR DEVICES WITHOUT PERMISSION	
TITLE: VGAP-CLB-AS-A1 Specification		DOCUMENT	ENS000061960	SPEC REV.
THEE TOAL OLD-AG-AL	opcomodion .	NO.	L14000001900	A5

# **Efficiency**



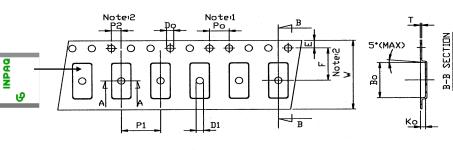
Frequency (MHz)	Efficiency (%)
2400	72.9
2450	74.8
2500	73.0
5000	74.3
5500	81.6
6000	71.9



UNLESS OTHER SPECIFIED X=± X.X=± ANGLES=±	TOLERANCES ON: X.XX= HOLEDIA=±	<u>G</u>	INPAQ TECHNOLOGY CO	)., LTD.
SCALE:	UNIT: mm	THIS DRAWIN	IGS AND SPECIFICATIONS ARE THE PRO	OPERTY OF
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DESIGNED BY:彭少君	APPROVED BY:謝立庭			
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		NO.	LN3000001900	A5

# 7. Taping Package and Label Marking:

- (1) Quantity/Reel: 2000pcs/Reel
- (2) Carrier tape dimensions



(Unit: mm)

	(
Symbol	Spec.
Po	4.00±0.1
P1	8.00±0.1
P2	2.00±0.05
Do	1.55±0.05
D1	1.50(MIN)
E	1.75±0.1
F	5.50±0.05
10Po	40.00±0.2
W	12.00±0.1
Т	0.25±0.05



 $A0 = 4.10 \pm 0.10 \text{ mm}$ 

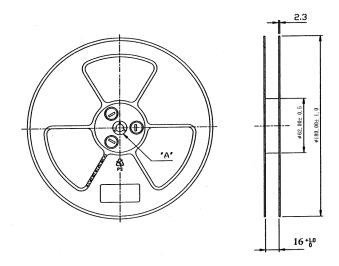
 $B0 = 5.60 \pm 0.10 \text{ mm}$ 

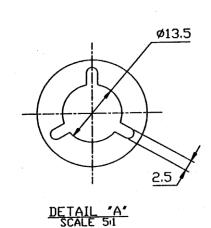
 $K0 = 1.02 \pm 0.10 \text{ mm}$ 

#### Notice:

- 1. 10 Sprocket hole pitch cumulative tolerance is ±0.1mm
- Pocket position relative to sprocket hole measured as true position of pocket not pocket hole.
- Ao & Bo measured on a place 0.3mm above the bottom of the pocket to top surface of the carrier.
- Ko measured from a plane on the inside bottom of the pocket to the top surface of the carrier.
- 5. Carrier camber shall be not than 1mm per 100mm through a length of 250mm.

### (3) Taping reel dimensions





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DESIGNED BY:彭少君	APPROVED BY:謝立庭	APPARATUS OR DEVICES WITHOUT PERMISSION		
TITLE: VGAP-CLB-AS-A1 Specification		DOCUMENT	ENS000061960	SPEC REV.
		NO	LN3000001300	Δ5

# 8. Environmental Characteristics:

This product is qualified according to AEC-Q200.

# (1) Reliability Test

Item	Condition	Specification
High Temperature Storage	150℃,1000hours	No Damaged
Temperature Cycling	-55°C 30min/125°C 30min → 1000 cycle	No Damaged
Biased Humidity	85°C 、85% RH,1000hours	No Damaged
Resistance to Solvent	Add Aqueous wash chemical OKEMCLEAN for 5 min	No Damaged
Mechanical Shock	1500G 0.5 ms , X,Y,Z axis 3 time	No Damaged
Vibration	<ol> <li>Frequency: 10 to 2000 Hz</li> <li>5g's for 20 min</li> <li>Duration time: 2hr for each in X,Y,Z</li> </ol>	No Damaged
Resistance to Soldering Heat	Brush flux and put the board into solder bath 260 $^\circ\!$	No Damaged
Solderability Test	<ol> <li>8 hours ± 15 min. steam conditioning</li> <li>Put the sample on board by tape.</li> <li>Brush flux and put the board into solder bath 260±5°C , 5±1 sec</li> </ol>	No Damaged
Board Flex	2mm for 60sec.	No Damaged
Termination strength (SMD)	1.8Kgf , 60sec	No Damaged

### (2) Storage condition

### (a) At warehouse:

The temperature should be within  $0 \sim 30^{\circ}$ C and humidity should be less than 60% RH. The product should be used within 1 year from the time of delivery.

#### (b) On board:

The temperature should be within -40  $\sim$  85°C and humidity should be less than 85% RH.

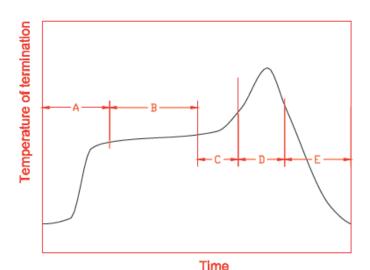
UNLESS OTHER SPECIFIED	TOLERANCES ON:			
$X=\pm$ $X.X=\pm$	X.XX =	G <sub>5</sub>	INPAQ TECHNOLOGY CO	)., LTD.
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TITLE: VGAP-CLB-AS-A1 Specification		DOCUMENT	ENS000061960	SPEC REV.
		NO.	E143000001900	A5

### (3) Operating temperature range

Operating temperature range: -40 ~ +125°C.

# 9. Recommended reflow soldering:

Reference: J-STD-020C



	111110	
1 <sup>st</sup> rising temperature	The normal to Preheating temperature	30s to 60s
Preheating	140°C to 160°C	60s to 120s
2 <sup>nd</sup> rising temperature	Preheating to 200°C	20s to 40s
Main heating	if 220℃	50s∼60s
	if 230℃	40s∼50s
	if 240℃	30s~40s
	if 250℃	20s~40s
	if 260°C	20s~40s

### (1) Soldering gun procedure

Regular cooling

Note the follows, in case of using solder gun for replacement.

(a) The tip temperature must be less than 350°C for the period within 3 seconds by using soldering gun under 30 W.

200°C to 100°C

(b) The soldering gun tip shall not touch this product directly.

### (2) Soldering volume

В С

D

Ε

Note that excess of soldering volume will easily get crack the body of this product.

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DESIGNED BY:彭少君	APPROVED BY:謝立庭	APPARATUS OR DEVICES WITHOUT PERMISSION		
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1°C/s ~ 4°C/s